



6/4/99

NIC COMPONENTS CORP.

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WASHING GUIDELINE

PRODUCTS: SMT FILM CHIP CAPACITORS SERIES: NSFC & NSPC

SUB: WASHING GUIDELINES

These *stacked film* style devices do not have protective coatings (common to leaded and molded case SMT style film capacitors) to prevent the penetration or absorption of moisture, fluxes, detergents or solvents encountered during circuit board assembly and cleaning operations. As a result, the following washing guidelines and precautions are suggested by NIC:

1. Use solder pastes, fluxes and cleaning detergents with halogen content below 0.1%.
2. Solvent cleaning in Isopropyl Alcohol (IPA), Trichloroethane, Silicon, Freon or HCFC141B-NS is recommended.
3. Cleaning using interfacial active agents; Terpene, Dichloroethane, Trichloroethylene, Toluene, Xylene and MEK is not endorsed.
4. Water washing using de-ionized water is possible, although care must be taken to eliminate moisture that may have penetrated the part. Experimentation under actual production cleaning and drying conditions is suggested. The de-ionized water should be free of detergents and chemicals. Drying should be performed for 30 minutes at +85°C. Low insulation resistance (high leakage current) may indicate insufficient drying technique.
5. These parts are compatible with immersion, solvent steam and ultrasonic* washing techniques for duration's up to 5 minutes, at temperatures up to +50°C.

* - Testing under actual ultrasonic cleaning conditions, for damage to component, is suggested.

ISO 9002 REGISTERED